Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KM-27SURCK-03	Hyper Red (AlGaInP)	Water Clear	1500	2400	20°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	I⊧=20mA
lr	Reverse Current	Hyper Red		10	uA	Vr=5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	185	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

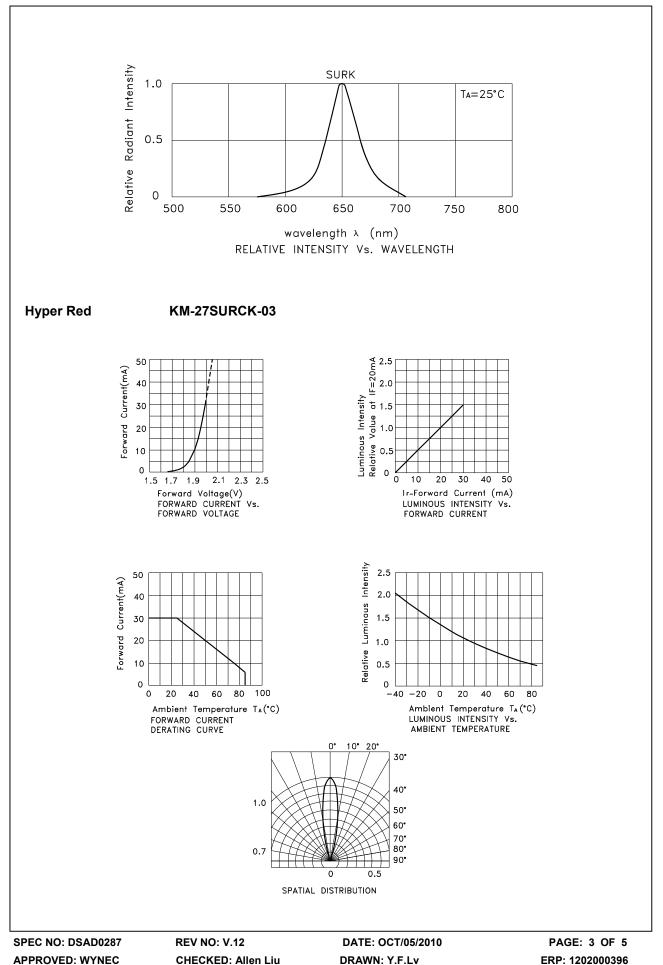
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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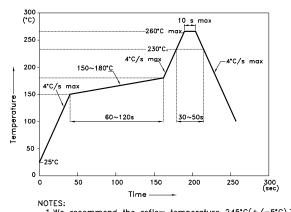
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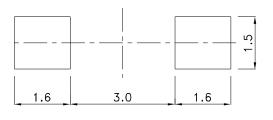
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

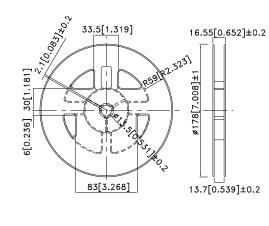


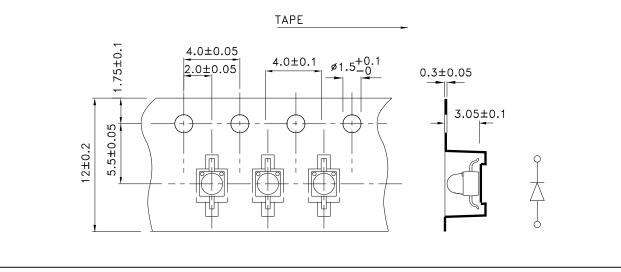
NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.











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Tape Dimensions

(Units : mm)

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